

Does not contain environment polluting halogen such as Chlorine or Bromine, this is Sn-3.0Ag-0.5Cu halogen free solder paste.

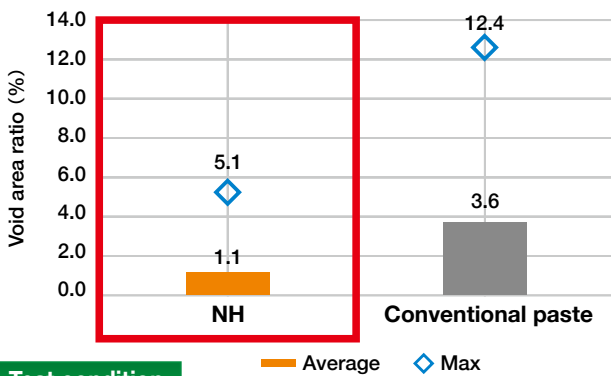
Characteristics

- Reduces voids, realizes highly reliable solder joint
- Applicable to wide range of reflow profiles, and products

Void performance

- Low void generation

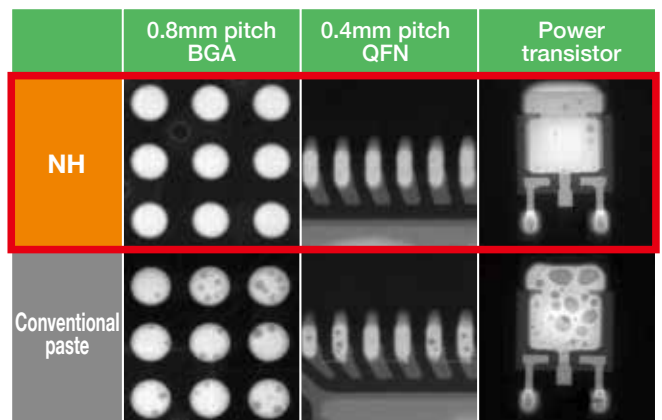
Void area ratio (BGA)



Test condition

- Substrate : FR4/Cu pad
- Mask thickness : 120μm
- Reflow condition : Center reflow profile (Below)
- O₂ concentration : 1,500ppm

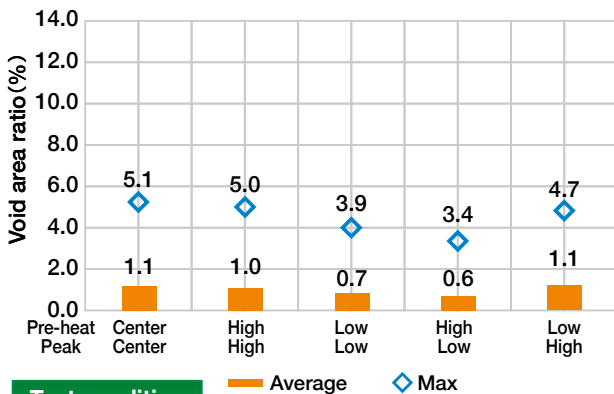
Void results of each components (X-ray)



Void performance for different reflow profiles

- Applicable to wide range of profiles

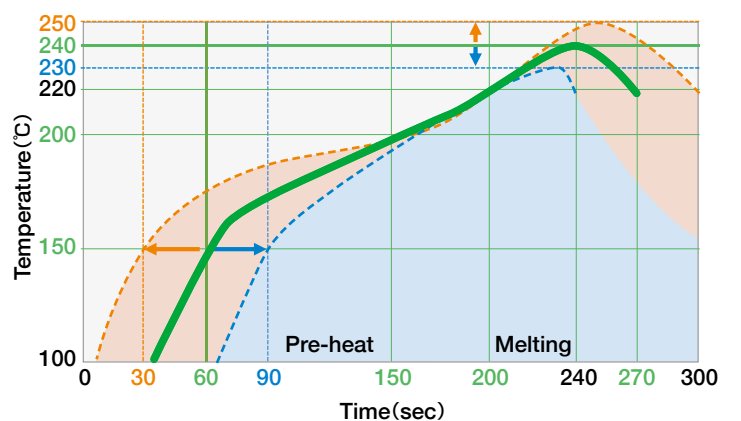
Void area ratio (BGA)



Test condition

- Substrate : FR4/Cu pad
- Mask thickness : 120μm
- Reflow condition : see right figure
- O₂ concentration : 1,500ppm

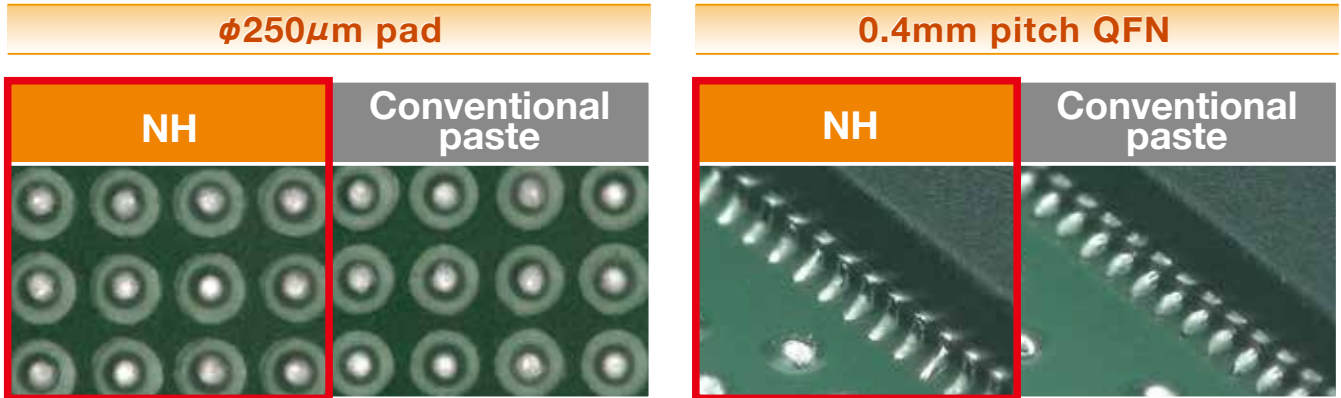
Reflow profile



Center reflow profile

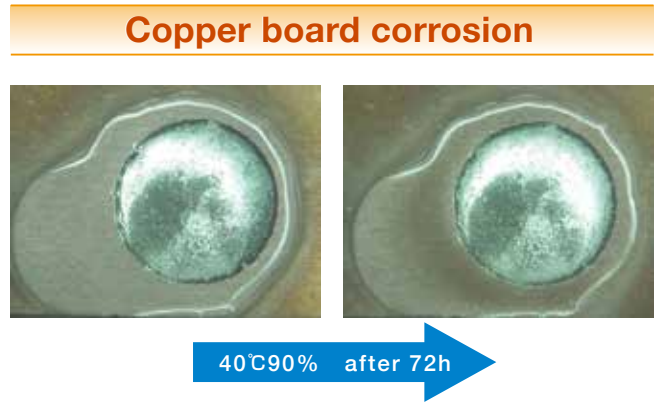
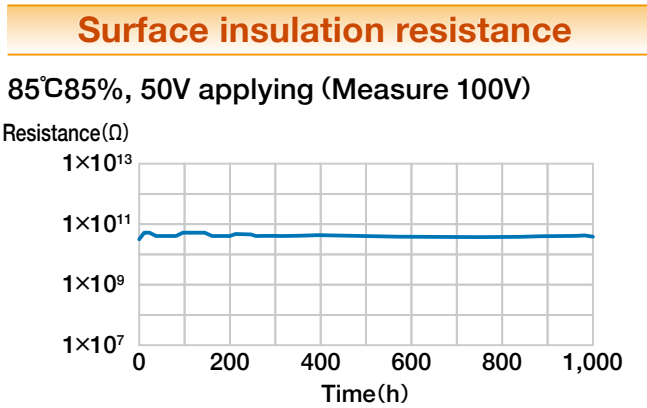
Wettability

● Good wettability



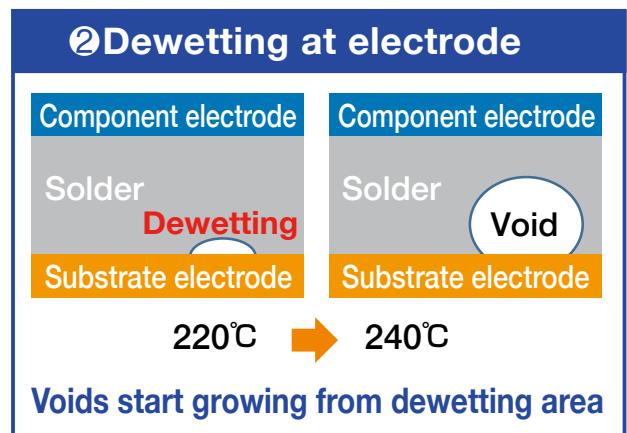
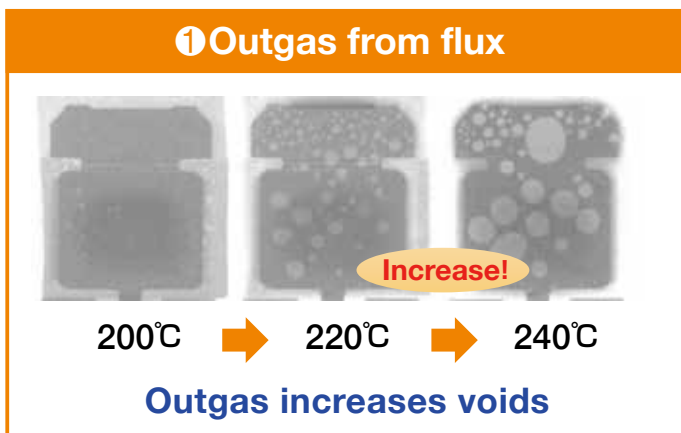
Reliability

● High insulation resistance and corrosion resistant



Void improvement mechanism

● Void formation factors



NH Achieve low void by reducing outgas and improving wettability